Micron Technology, Inc.
8000 S. Federal Way
PO Box 6
Boise, ID United States

NAND MCP Silicon Improvement: Bond Pad Metallization Change

PCN: 33253

Published: 2019-06-25

Revision History:

Revision 2, 2020-02-19: This document supersedes Revision 1, dated 2019-09-23 and the original PCN #33253, dated 2019-06-25.

The first table in the Description below has been updated to show that polyimide is included in the Bond Pad Metallization Change. The updated information in the table is reflected in **bold** font.

Type: Manufacturing Process Change

Description: Micron will convert the NAND bond pad metallization from Ni/Pd to Aluminum (Al). Other DRAM/NAND technologies at Fab 6 use Al bond process and is proven to be more robust.

During the conversion period, customers will receive a mix of both bond pad types, however, the change will not impact the final packaged products. Micron has complete traceability via Lot ID number, Sales Order number, or Purchase Order number, etc. Full conversion to the new process is planned by **June 2020**. Micron reserves the right to ship either ALM2 or NiPd manufactured until the NiPd inventory has been depleted.

Was	Is
Layers	Layers
Metal 2: Cu+ Ni/Pd (Plating)	Metal2: Al Sputter
Non-Polyimide	**Polyimide**

Product	Qual/Sample Available	Product Ship Date
J4Q2	7/31/2019	6/30/2020
J4MK	7/31/2019	6/30/2020
J84F	12/2/2019	6/30/2020

Reason:	Improved Product Quality and Reliability, Manufacturing Efficiency
Product Affected:	NAND MCP (J4Q2, J4MK, J84F)

Affected Micron Part Number	Recommended Replacement	Customer Part Number
Component		
MT29AZ5A3CHHWD-18AAT.84F		
MT29AZ5A3CHHWD-18AIT.84F		**?**
MT29C1G12MAAIVAMD-5 IT		
MT29C1G12MAAJVAMD-5 IT		**557-1997-2-ND**
MT29C4G48MAYBBAKS-48 IT		
MT29C4G48MAYBBAMR-48 IT		**557-1998-2-ND**
MT29C4G48MAZBBAKB-48 IT		**557-1832-2-ND, ?**
MT29C4G48MAZBBAKS-48 IT		**557-1999-2-ND**
MT29RZ4B2DZZHHWD-18I.84F		**557-1889-2-ND**

*Materials that have been ordered are in **bold**.

Method of Identification:	none
Micron Sites Affected:	Fab 6 - US
Sample Available:	2019-07-31
Qual Data Available:	2019-07-31
Product Ship Date:	2020-06-30

NOTE: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

Thank you